IN THE CLAIMS

1. – 6. (Canceled)

7. (Currently amended) An apparatus comprising:

dielectric;

conductive material on the dielectric, the conductive material defining a plurality of spaced lines each line having a proximal end and a distal end;

a plurality of drivers, each driving the proximal end of a respective one of the spaced lines, each driver receiving a common input signal; and

a ground plane in contact with the dielectric on a side thereof opposite the spaced lines; ~~The apparatus according to claim 6, in which~~ wherein the *h:s* ratio associated with the height of the conductive lines relative to their spacing therebetween is greater than the *w:t* ratio associated with the width of the center conductive line relative to a thickness of the dielectric.

8. (Previously presented) The apparatus according to claim 7, in which the *h:s* ratio is at least 1.5 times greater than the *w:t* ratio.

9. (Previously presented) The apparatus according to claim 8, in which the *h:s* ratio is at least greater than the *w:t* ratio multiplied by the relative dielectric constant of the dielectric.

10. (Canceled)

11. (Currently amended) An apparatus comprising:

dielectric;

conductive material on the dielectric, the conductive material defining a plurality of spaced lines each line having a proximal end and a distal end;

a plurality of drivers, each driving the proximal end of a respective one of the spaced lines, each driver receiving a common input signal; and

second dielectric over and between the lines;

~~The apparatus according to claim 10, in which~~ wherein the second dielectric comprises a dielectric constant the same as that of the dielectric beneath the conductive material.

12.-13. (Canceled)

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14. (Currently amended) A transmission line structure comprising:

a ground plane;

a dielectric over the ground plane;

a plurality of conductive lines over the dielectric, each conductive line comprising:

opposite primary faces, and

opposite secondary faces defining their height,

one of the secondary faces in contact with the dielectric to support the conductive line relative thereto;

primary faces of adjacent conductive lines defining a gap therebetween, the gap distance less than the height of the conductive lines; and

a plurality of amplifiers to drive respective conductive lines of the plurality of conductive lines, in which the amplifiers of the plurality comprise inputs electrically coupled in common to a signal node;

~~The transmission line structure according to claim 12, in which~~ wherein the dielectric comprises a thickness *t*, and one of the conductive lines comprises a width *W* between its primary faces; the ratio *h:s* for the height *h* of the conductive lines relative to the gap distance *s* being greater than the ratio *W:t* for the width *W* of the conductive line relative to the dielectric thickness *t*.

15. (Previously presented) The transmission line structure according to claim 14, in which the *h:s* ratio is at least 1/2 times greater than the *W:t* ratio.

16.-18. (Canceled)

19. (Currently amended) An apparatus comprising:

dielectric;

conductive material on the dielectric, the conductive material defining three spaced lines each line having a proximal end and a distal end;

a plurality of drivers, each driving the proximal end of a respective one of the spaced lines, each driver receiving a common input signal; and

second dielectric over and between the lines;

~~The transmission line structure according to claim 18, in which~~ wherein the dielectric comprises a thickness *t*, and the center one of the three conductive lines comprises a width *W* between its primary faces; the ratio *h:s* for the height *h* of the conductive lines relative to the

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gap distance s being greater than 1.5 times the ratio $W:t$ for the width W of the center conductive line relative to the dielectric thickness t.

20. (Previously presented) An integrated circuit comprising:

a dielectric having a surface;

a plurality of conductive lines against the dielectric for signal propagation, each conductive line having a source end to receive a signal and comprising:

a first edge against the surface of the dielectric;

opposing sidewalls extending away from the dielectric, and

a second edge opposite the first edge to define a height; and

a plurality of amplifiers, each associated with at least one of the conductive lines and driving the source end of the at least one of the conductive lines, each amplifier having an input coupled to a signal node common to each amplifier.

21. (Currently amended) [An] The integrated circuit according to claim 20, in which the height is at least 1.5 times greater than the spacing between the adjacent conductive lines.

22. (Currently amended) [An] The integrated circuit according to claim 21, in which the plurality of conductive lines comprises three, the middle conductive line disposed between two outer conductive lines and comprising a width defined by its opposing sidewalls.

23. (Currently amended) [An] The integrated circuit according to claim 20, further comprising a conductive layer against the dielectric opposite the plurality of conductive lines.

24. (Previously presented) The integrated circuit according to claim 22, further comprising a receiver connected to the other end of the middle conductive line.

25. (Previously presented) The integrated circuit according to claim 24 further comprising two dummy loads connected respectively to the other ends of the two outer conductive lines.

26. (Previously presented) The integrated circuit according to claim 25, the dummy loads presenting matched impedances to their respective conductive lines.

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27. – 31. (Canceled)

32. (Previously presented) A computer system having a processor comprising:

a substrate with an insulating layer; and

a plurality of conductive lines in contact with the insulating layer,

a center conductive line disposed between two other conductive lines of the plurality to define a gap distance therebetween; and

a data buffer to source a data signal to the plurality of conductive lines.

33. (Previously presented) The computer system according to claim 32, the processor further comprising a ground plane in contact with the insulating layer on a side opposite the plurality of conductive lines.

34. (Previously presented) The computer system according to claim 33, in which the center conductive line comprises a width W;
the insulating layer comprises a thickness t;
the h:s ratio for the height h of the conductive lines relative to the gap distance s being greater than the W:t ratio for the width W of the center conductive line relative to the thickness t of the insulating layer.

35. (Previously presented) The computer system according to claim 34, in which the h:s ratio is 1.5 times greater than the W:t ratio.

36. (Canceled).

37. (Previously presented) The computer system according to claim 32, the processor further comprising a data receiver to receive a data signal from the plurality of conductive lines at a location remote the data buffer.

38. (Previously presented) The computer system according to claim 37, in which the data receiver is coupled to receive a data signal from the center conductor of the plurality.

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39. (Previously presented) The computer system according to claim 38, the processor further comprising dummy loads coupled to the outer conductive lines.

40. (Previously presented) The computer system according to claim 39, in which the dummy loads are coupled to the outer conductive lines at locations thereof proximate the coupling of the data receiver to the center conductive line.

41. (Previously presented) The computer system according to claim 40, the processor further comprising separate drivers for each of the plurality of conductive lines, each driver to receive the data signal from the data buffer and to drive its respective conductive line of the plurality.

42. (Previously presented) The computer system according to claim 32, the processor further comprising dielectric over the conductive lines and the insulating layer.

43. (Previously presented) The computer system according to claim 42, in which the dielectric is over and between the conductive lines.

44. (Currently amended) [A] The computer system according to claim 43, in which the dielectric comprises a material of dielectric constant substantially the same as the insulating layer.

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